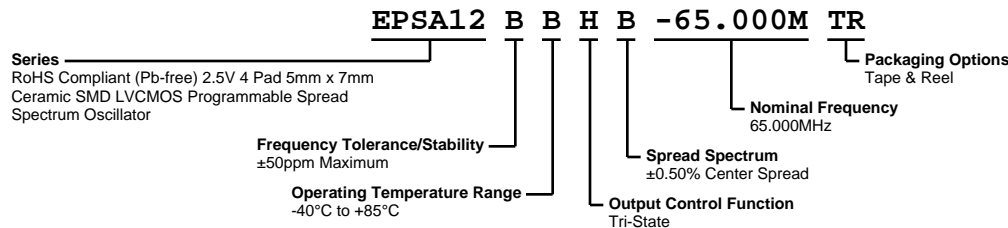


# EPSA12BBHB-65.000M TR



## ELECTRICAL SPECIFICATIONS

Nominal Frequency	65.000MHz
Frequency Tolerance/Stability	±50ppm Maximum (Inclusive of all conditions: Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration.)
Operating Temperature Range	-40°C to +85°C
Supply Voltage	2.5Vdc ±5%
Maximum Supply Voltage	-0.5Vdc to +3.2Vdc
Input Current	22mA Maximum
Output Voltage Logic High (Voh)	90% of Vdd Minimum (IOH=-8mA)
Output Voltage Logic Low (Vol)	10% of Vdd Maximum (IOL=+8mA)
Rise/Fall Time	3nSec Maximum (Measured at 10% to 90% of Waveform)
Duty Cycle	50% ±5(%) (Measured at 50% of waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Output Control Function	Tri-State (Disabled Output: High Impedance)
Tri-State Input Voltage (Vih and Vil)	70% of Vdd Minimum or No Connection to Enable Output, 30% of Vdd Maximum to Disable Output
Tri-State Output Disable Time	100nSec Maximum
Tri-State Output Enable Time	100nSec Maximum
Disable Current	20mA Maximum (Unloaded; Pad 1=Ground)
Spread Spectrum	±0.50% Center Spread
Modulation Frequency	30kHz Minimum, 32kHz Typical, 45kHz Maximum
Period Jitter	100pSec Maximum (Cycle to Cycle; Spread Spectrum-On)
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

# EPSA12BBHB-65.000M TR

## MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Tri-State
2	Case Ground
3	Output
4	Supply Voltage

LINE	MARKING
1	<b>ECLIPTEK</b>
2	<b>65.000M</b>
3	<b>SXXXXX</b> <i>S=Configuration Designator</i> <i>XXXXX=Ecliptek</i> <i>Manufacturing Identifier</i>

## Suggested Solder Pad Layout

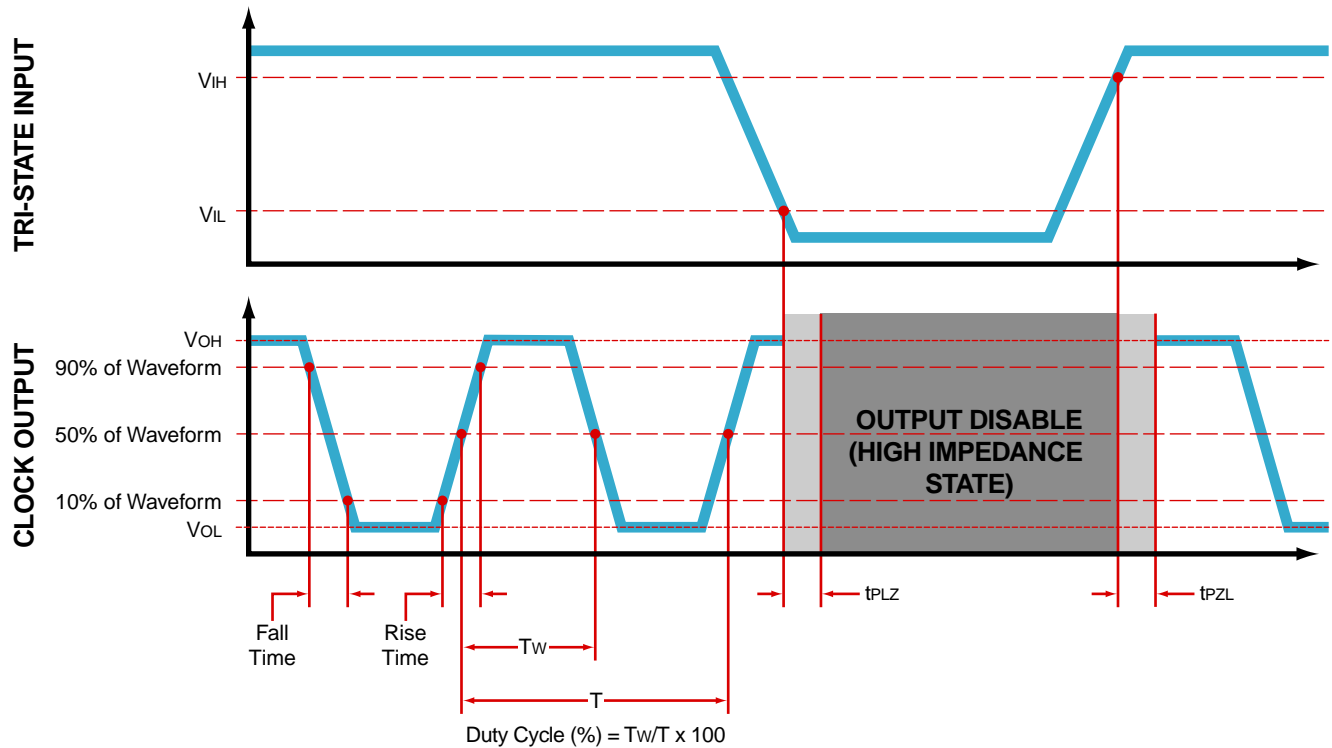
All Dimensions in Millimeters



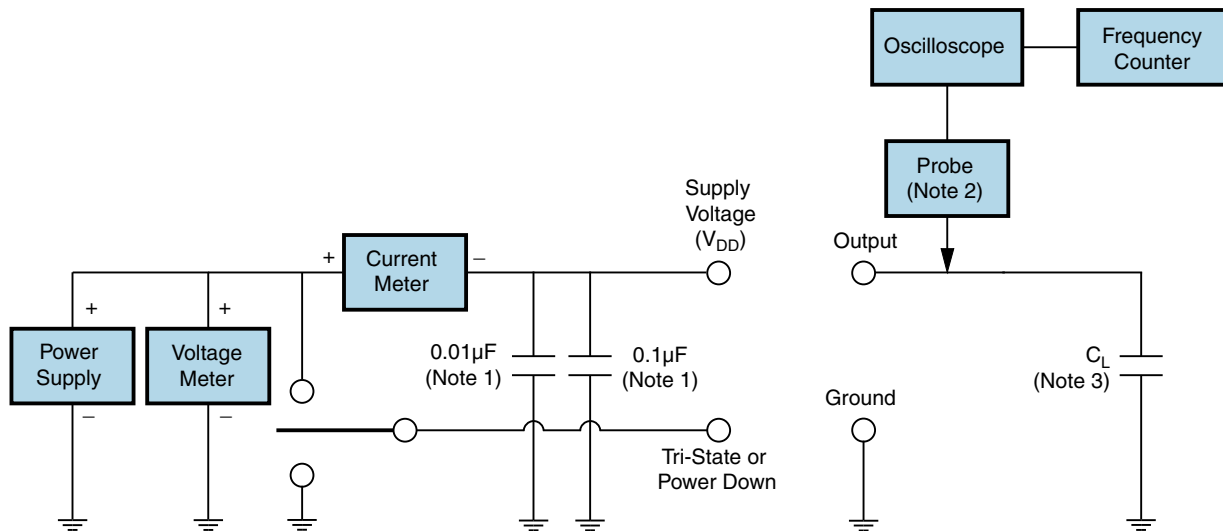
All Tolerances are  $\pm 0.1$

# EPSA12BBHB-65.000M TR

## OUTPUT WAVEFORM & TIMING DIAGRAM



## Test Circuit for CMOS Output



Note 1: An external 0.01 $\mu$ F ceramic bypass capacitor in parallel with a 0.1 $\mu$ F high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

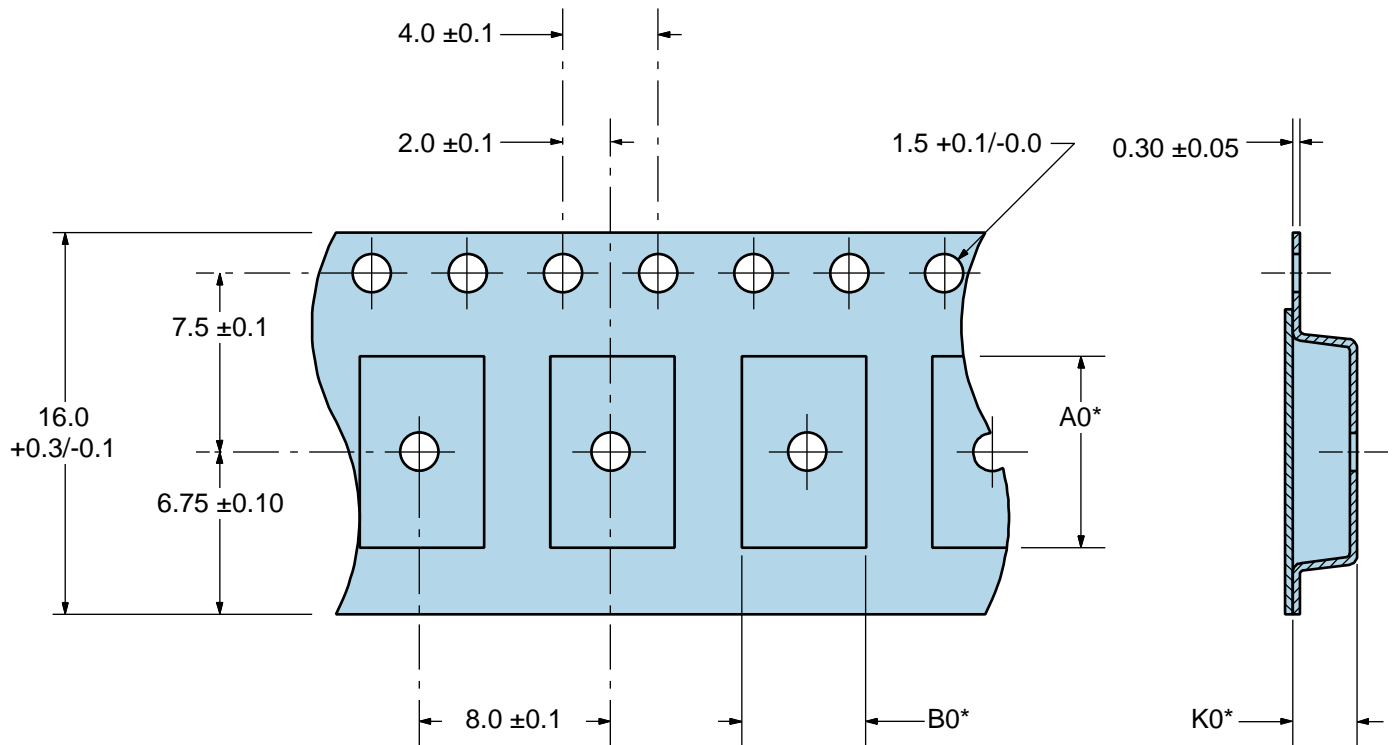
Note 2: A low input capacitance (<12pF), 10X Attenuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value CL includes sum of all probe and fixture capacitance. See applicable specification sheet for 'Load Drive Capability'.

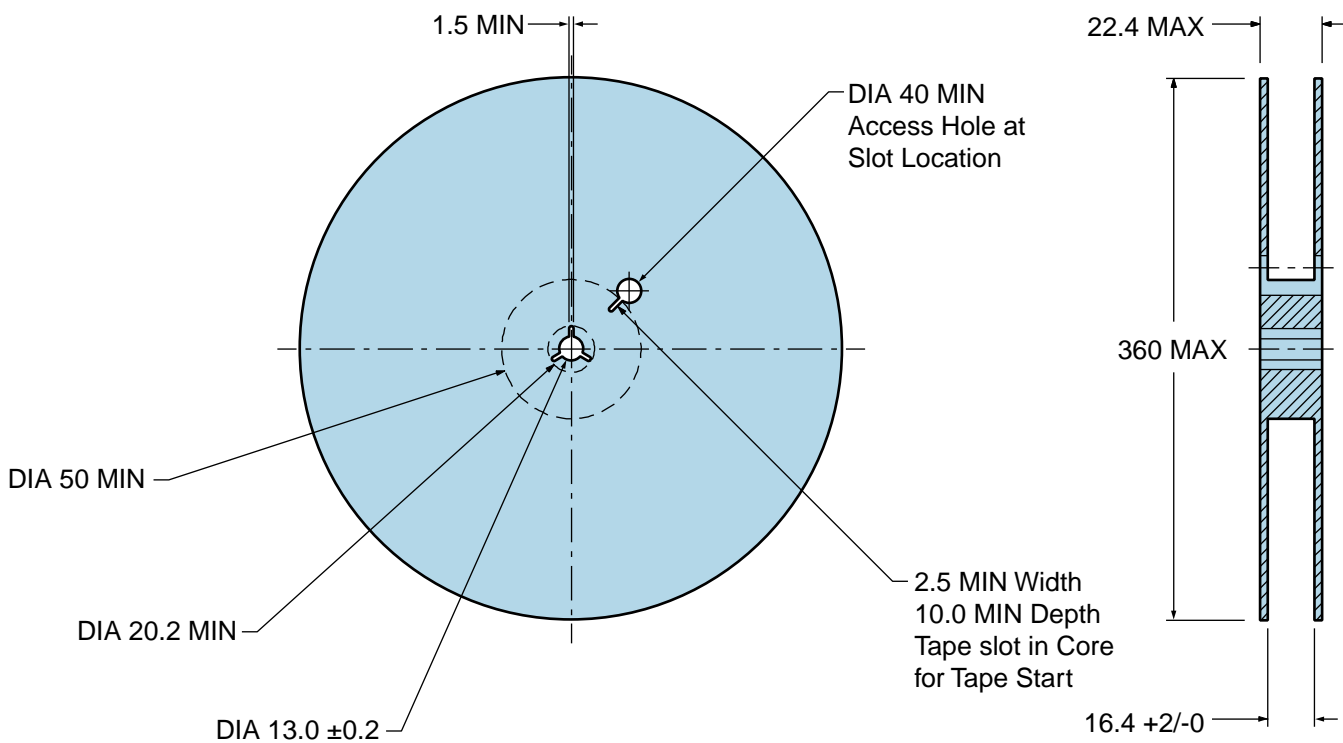
# EPSA12BBHB-65.000M TR

## Tape & Reel Dimensions

Quantity Per Reel: 1,000 Units



\*Compliant to EIA 481A



## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

<b><math>T_S</math> MAX to <math>T_L</math> (Ramp-up Rate)</b>	3°C/second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_S$ MIN)	150°C
- Temperature Typical ( $T_S$ TYP)	175°C
- Temperature Maximum ( $T_S$ MAX)	200°C
- Time ( $t_s$ MIN)	60 - 180 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	3°C/second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	217°C
- Time ( $t_L$ )	60 - 150 Seconds
<b>Peak Temperature (<math>T_P</math>)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (<math>T_P</math> Target)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	20 - 40 seconds
<b>Ramp-down Rate</b>	6°C/second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

<b><math>T_S</math> MAX to <math>T_L</math> (Ramp-up Rate)</b>	5°C/second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_S$ MIN)	N/A
- Temperature Typical ( $T_S$ TYP)	150°C
- Temperature Maximum ( $T_S$ MAX)	N/A
- Time ( $t_s$ MIN)	60 - 120 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	5°C/second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	150°C
- Time ( $t_L$ )	200 Seconds Maximum
<b>Peak Temperature (<math>T_P</math>)</b>	240°C Maximum
<b>Target Peak Temperature (<math>T_P</math> Target)</b>	240°C Maximum 1 Time / 230°C Maximum 2 Times
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time
<b>Ramp-down Rate</b>	5°C/second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	N/A
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

### Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

### High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)